WEST Search History

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DATE: Wednesday, September 22, 2004

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	DB=US	SPT; PLUR=YES; OP=ADJ			
	L3	L1 and 134/\$.ccls.	19		
	L2	L1 and 134/.ccls.	0		
	L1	quartz with (metal or steel or aluminum) with wall	651		

END OF SEARCH HISTORY

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L5: Entry 10 of 11

File: USPT

May 26, 1992

DOCUMENT-IDENTIFIER: US 5115576 A

TITLE: Vapor device and method for drying articles such as semiconductor wafers with substances such as isopropyl alcohol

 $\frac{\text{Current US Cross Reference Classification}}{134/21} \hspace{0.1cm} \textbf{(1):} \\$

CLAIMS:

3. A device according to claim 1, where said vacuum process chamber includes a $\underline{\text{quartz liner}}$.

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L3: Entry 1 of 19

File: USPT

Mar 16, 2004

DOCUMENT-IDENTIFIER: US 6706334 B1

TITLE: Processing method and apparatus for removing oxide film

Detailed Description Text (35):

The treatment vessel 110 is constituted of <u>aluminum</u> materials and its inner <u>wall is provided with quartz</u> (SiO.sub.2) linings 113 and 114 to be protected from <u>metal</u> pollution, erosion or the like. The treatment vessel 110 can be formed as a housing whose transverse plane may have various shapes such as a circle, a square and a polygon. A bottom plate 112 having a predetermined thickness is fixed to the bottom of the treatment vessel 110. A base 129 is disposed on the bottom plate 112, and a cylindrical susceptor 120 is provided on the base 129. The wafer W is placed on the top of the susceptor 120 and clamped by a quartz—made clamp ring 121. A jacket (or a pipe) 122 for holding a chiller and a heat exchanger 123 are included in the susceptor 120. The jacket 122 and heat exchanger 123 can be formed integrally as one component. The chiller is supplied from a chiller supply unit 142 into the jacket 122 through a cooling pipe 143 to cool the wafer W down to a given temperature, such as a temperature not higher than room temperature.

<u>Current US Cross Reference Classification</u> (1): 134/1.1

<u>Current US Cross Reference Classification</u> (2): 134/1.2

<u>Current US Cross Reference Classification</u> (3): 134/3

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L2: Entry 1 of 1

File: DWPI

Jan 28, 1998

DERWENT-ACC-NO: 1996-334173

DERWENT-WEEK: 200328

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TITLE: Wet chemical treatment installation for substrate plates - has lifting device with respective transport carriages for substrate plates and substrate plate holder

INVENTOR: DURST, J; SCHULZ, W ; SIGEL, H

PATENT-ASSIGNEE:

ASSIGNEE CODE
STEAG MICROTECH GMBH DONAUESCHINGEN STGG
STEAG MICROTECH GMBH STGG
STEAGMICRO TECH GMBH STGG

PRIORITY-DATA: 1995DE-1046990 (December 15, 1995), 1995DE-1000239 (January 5, 1995)

	Search Selected Sea	rch ALL	Clear				
PATENT-FAMILY:							
PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC			
CN 1171858 A	January 28, 1998		000	H01L021/00			
WO 9621241 A1	July 11, 1996	G	045	H01L021/00			
DE 19546990 A1	July 11, 1996		021	B65G049/04			
DE 19546990 C2	July 3, 1997		018	B65G049/04			
DE 19549487 A1	August 7, 1997		045	B65G049/04			
FI 9702733 A	June 25, 1997		000	H01L000/00			
DE 19549488 A1	September 4, 1997		000	B65G049/04			
DE 19549490 A1	September 11, 1997		001	B65G049/04			
EP 801814 A1	October 22, 1997	G	000	H01L021/00			
☐ JP 10503327 W	March 24, 1998		040	H01L021/304			
KR 98701133 A	April 30, 1998		000	H01L021/00			
US 5902402 A	May 11, 1999		000	B05C003/00			
☐ JP 3088463 B2	September 18, 2000		016	H01L021/304			

DE 19549487 C2	November 16, 2000	000	B65G049/04
DE 19549490 C2	January 18, 2001	000	B65G049/04
TW 399224 A	July 21, 2000	000	H01L021/00
DE 19549488 C2	August 2, 2001	000	B65G049/04
EP 801814 B1	August 29, 2001 G	000	H01L021/00
DE 59509568 G	October 4, 2001	000	H01L021/00
KR 275166 B	January 15, 2001	000	H01L021/00

DESIGNATED-STATES: CA CN FI JP KR SG US AT BE CH DE DK ES FR GB GR IE IT LU MC NL PT SE AT BE CH DE DK ES FR GB GR IE IT LI LU NL PT SE AT BE CH DE DK ES FR GB GR IE IT LI LU NL PT SE

CITED-DOCUMENTS: EP 523836; FR 2586658; GB 2178594; US 5301700

APPLICATION-DATA:

PU.	B-NO	APPL-DATE			APPL-NO	DESCRIPTOR
CN	1171858A	December	29,	1995	1995CN-0197255	
CN	1171858A	December	29,	1995	1995WO-EP05153	
CN	1171858A				WO 9621241	Based on
WO	9621241A1	December	29,	1995	1995WO-EP05153	
DE	19546990A1	December	15,	1995	1995DE-1046990	
DE	19546990C2	December	15,	1995	1995DE-1046990	
DE	19549487A1	December	15,	1995	1995DE-1046990	Div ex
DE	19549487A1	December	15,	1995	1995DE-1049487	
DE	19549487A1				DE <u>19546990</u>	Div ex
FI	9702733A	December	29,	1995	1995WO-EP05153	
FI	9702733A	June 25,	1997	,	1997FI-0002733	
DE	19549488A1	December	15,	1995	1995DE-1046990	Div ex
DE	19549488A1	December	15,	1995	1995DE-1049488	
DE	19549488A1				DE <u>19546990</u>	Div ex
DE	19549490A1	December	15,	1995	1995DE-1046990	Div ex
DE	19549490A1	December	15,	1995	1995DE-1049490	
DE	19549490A1				DE <u>19546990</u>	Div ex
EΡ	801814A1	December	29,	1995	1995EP-0943224	
EΡ	801814A1	December :	29,	1995	1995WO-EP05153	
EΡ	801814A1				WO 9621241	Based on
JP	10503327W	December :	29,	1995	1995WO-EP05153	
JΡ	10503327W	December :	29,	1995	1996JP-0520722	
JР	10503327W				WO 9621241	Based on
KR	98701133A	December 2	29,	1995	1995WO-EP05153	
KR	98701133A	July 1, 19	997		1997KR-0704546	
KR	98701133A				WO 9621241	Based on
US	5902402A	December 2	29,	1995	1995WO-EP05153	

US	5902402A	July 3, 1997		1997US-0875408	
US	5902402A			WO 9621241	Based on
JΡ	3088463B2	December 29, 19	995	1995WO-EP05153	
JΡ	3088463B2	December 29, 19	995	1996JP-0520722	
JP	3088463B2			JP 10503327	Previous Publ.
JP	3088463B2			WO 9621241	Based on
DE	19549487C2	December 15, 19	995	1995DE-1046990	Div ex
DE	19549487C2	December 15, 19	995	1995DE-1049487	
DE	19549487C2			DE <u>19546990</u>	Div ex
DE	19549490C2	December 15, 19	995	1995DE-1046990	Div ex
DE	19549490C2	December 15, 19	995	1995DE-1049490	
DE	19549490C2			DE <u>19546990</u>	Div ex
TW	399224A	January 5, 1996	5	1996TW-0100109	
DE	19549488C2	December 15, 19	95	1995DE-1046990	Div ex
DE	19549488C2	December 15, 19	95	1995DE-1049488	
DE	19549488C2			DE <u>19546990</u>	Div ex
EΡ	801814B1	December 29, 19	95	1995EP-0943224	
ΕP	801814B1	December 29, 19	95	1995WO-EP05153	
EΡ	801814B1			WO 9621241	Based on
DE	59509568G	December 29, 19	95	1995DE-0509568	
DE	59509568G	December 29, 19	95	1995EP-0943224	
DE	59509568G	December 29, 19	95	1995WO-EP05153	
DE	59509568G			EP 801814	Based on
DE	59509568G			WO 9621241	Based on
KR	275166B	December 29, 19	95	1995WO-EP05153	
KR	275166B	July 1, 1997		1997KR-0704546	
KR	275166B		•	KR 98701133	Previous Publ.
KR	275166B			WO 9621241	Based on

399224 A , DE 19549488 C2 INT-CL (IPC): B05C 3/00; B65G 49/04; B65G 49/07; H01L 0/00; H01L 21/00; H01L 21/30; H01L 21/304; H01L 21/306; H01L 21/68

ABSTRACTED-PUB-NO: EP 801814B BASIC-ABSTRACT:

The installation (20) has a container (21) holding the treatment fluid (23) into which a holder (17) for the substrate plates (25) is lowered. Continuous lifting in and out of the substrate plate holder and the substrate plates relative to the treatment fluid is obtained via a lifting device with one transport carriage for the substrate plates and a second transport carriage for the holder.

The transport carriages for the substrate plates and the holder are coupled together via a linkage and displaced relative to a vertical guide rail, with the lifting drive acting on the first transport carriage.

USE - For uniform surface treatment of silicon wafers.
ABSTRACTED-PUB-NO:

US 5902402A EQUIVALENT-ABSTRACTS:

The installation (20) has a container (21) holding the treatment fluid (23) into which a holder (17) for the substrate plates (25) is lowered. Continuous lifting in and out of the substrate plate holder and the substrate plates relative to the treatment fluid is obtained via a lifting device with one transport carriage for the substrate plates and a second transport carriage for the holder.

The transport carriages for the substrate plates and the holder are coupled together via a linkage and displaced relative to a vertical guide rail, with the lifting drive acting on the first transport carriage.

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The installation (20) has a container (21) holding the treatment fluid (23) into which a holder (17) for the substrate plates (25) is lowered. Continuous lifting in and out of the substrate plate holder and the substrate plates relative to the treatment fluid is obtained via a lifting device with one transport carriage for the substrate plates and a second transport carriage for the holder.

The transport carriages for the substrate plates and the holder are coupled together via a linkage and displaced relative to a vertical guide rail, with the lifting drive acting on the first transport carriage.

USE - For uniform surface treatment of silicon wafers.

WO 9621241A

CHOSEN-DRAWING: Dwg.3/16

TITLE-TERMS: WET CHEMICAL TREAT INSTALLATION SUBSTRATE PLATE LIFT DEVICE RESPECTIVE TRANSPORT CARRIAGE SUBSTRATE PLATE SUBSTRATE PLATE HOLD

DERWENT-CLASS: P42 Q35 U11

EPI-CODES: U11-C06A1B; U11-C07B;

SECONDARY-ACC-NO:

Non-CPI Secondary Accession Numbers: N1996-281583

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